

WHAT IS CLAIMED IS:

1. A unit control panel provided in at least one of units of a substrate processing apparatus, the substrate processing apparatus processing a substrate with transferring the substrate between the units assembled together, comprising
5 a test control section configured to perform a substrate transfer test for a unit provided with the unit control panel using a substrate table which is installed outside the unit while the unit is not assembled together with another unit.
2. The unit control panel according to claim 1, wherein
the test control section performs the substrate transfer test by transporting the
10 substrate placed in the unit to the substrate table and mounting the substrate on the substrate table by a substrate transport mechanism which is provided in the unit or receiving the substrate mounted on the substrate table and transporting the substrate into the unit by the transport mechanism.
3. The unit control panel according to claim 1 or 2, wherein
15 the substrate table is installed for the substrate transfer test at a location where a substrate transfer section of another unit which is used at a time of transfer of the substrate between the unit and another unit is located when the unit and another unit are assembled together.
4. The unit control panel according to any one of claims 1 to 3, wherein
20 the substrate processing apparatus includes a

polishing unit configured to polish the substrate and mount the polished substrate on a temporary table, and a cleaning unit configured to clean and dry the substrate mounted on the temporary table, and the unit control panel is provided in the cleaning unit,

the substrate table is installed for the substrate transfer test instead of the
5 temporary table at a location where the temporary table is located when the polishing unit and the cleaning unit are assembled together, and

the test control section of the unit control panel provided in the cleaning unit performs the substrate transfer test by receiving the substrate mounted on the substrate table and transporting the substrate into the cleaning unit by a substrate transport
10 mechanism which is provided in the cleaning unit.

5. The unit control panel according to any one of claims 1 to 3, wherein

the substrate processing apparatus includes a polishing unit configured to polish the substrate, a cleaning unit configured to clean and dry the substrate polished by the polishing unit, and a loading/unloading unit configured to load the substrate onto
15 a lifter in the polishing unit and unload the substrate mounted on a substrate drying module in the cleaning unit, and the unit control panel is provided in the loading/unloading unit,

the substrate table is installed for the substrate transfer test instead of the lifter at a location where the lifter is located when the polishing unit and the

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loading/unloading unit are assembled together and is installed for the substrate transfer test instead of the drying module at a location where the drying module is located when the cleaning unit and the loading/unloading unit are assembled together, and

the test control section of the unit control panel provided in the loading/unloading unit performs the substrate transfer test by transporting the substrate placed in the loading/unloading unit to the substrate table and mounting the substrate on the substrate table by a substrate transport mechanism which is provided in the loading/unloading unit and receiving the substrate mounted on the substrate table and transporting the substrate into the loading/unloading unit by the transport mechanism.

6. A substrate transfer test method in at least one of units of a substrate processing apparatus, the substrate processing apparatus processing a substrate with transferring the substrate between the units assembled together, comprising:

installing a substrate table outside the at least one unit while the at least one unit is not assembled together with another unit; and

performing a substrate transfer test by selecting a scenario for which a transport route for the substrate is presented as a plurality of blocks at a unit control panel for the at least one unit using the substrate table.

7. The substrate transfer test method according to claim 6, wherein

the substrate transfer test is performed by transporting the substrate placed in the at least one unit to

the substrate table and mounting the substrate on the substrate table by a substrate transport mechanism which is provided in the at least one unit or receiving the substrate mounted on the substrate table and transporting the substrate into the at least one unit by the transport mechanism.

5 8. The substrate transfer test method according to claim 6 or 7, wherein
 the substrate table is installed for the substrate transfer test at a location where a substrate transfer section of another unit which is used at a time of transfer of the substrate between the unit and another unit is located when the unit and another unit are assembled together.

10 9. The substrate transfer test method according to any one of claims 6 to 8, wherein

 the substrate processing apparatus includes a polishing unit configured to polish the substrate and mount the polished substrate on a temporary table and a cleaning unit configured to clean and dry the substrate mounted on the temporary table,
15 and the substrate transfer test is performed in the cleaning unit,

 the substrate table is installed for the substrate transfer test instead of the temporary table at a location where the temporary table is located when the polishing unit and the cleaning unit are assembled together, and

 the substrate transfer test is performed by receiving the substrate mounted on
20 the substrate table and transporting the substrate into the cleaning unit by a substrate transport mechanism which is provided in the cleaning unit.

10. The substrate transfer test method according to any one of claims 6 to 8, wherein

the substrate processing apparatus includes a polishing unit configured to polish the substrate, a cleaning unit configured to clean and dry the substrate polished by the polishing unit, and a loading/unloading unit configured to load the substrate onto a lifter in the polishing unit and unload the substrate mounted on a substrate drying module in the cleaning unit, and the substrate transfer test is performed in the loading/unloading unit,

the substrate table is installed for the substrate transfer test instead of the lifter at a location where the lifter is located when the polishing unit and the loading/unloading unit are assembled together and is installed for the substrate transfer test instead of the drying module at a location where the drying module is located when the cleaning unit and the loading/unloading unit are assembled together, and

the substrate transfer test is performed by transporting the substrate placed in the loading/unloading unit to the substrate table installed instead of the lifter and mounting the substrate on the substrate table by a substrate transport mechanism which is provided in the loading/unloading unit and receiving the substrate mounted on the substrate table installed instead of the drying module and transporting the substrate into the loading/unloading unit by the transport mechanism.

11. A substrate processing apparatus for processing a

substrate, comprising:

at least one unit which is each provided with a unit control panel, the unit including a test control section configured to perform a substrate transfer test for the unit using a substrate table which is installed outside the unit while the unit is not assembled together with another unit; and

another unit which is to be assembled together with the unit,

wherein the substrate processing apparatus processes a substrate and transfers the substrate between the unit and another unit assembled together.

12. The substrate processing apparatus according to claim 11, wherein

the test control section performs the substrate transfer test by transporting the substrate placed in the unit to the substrate table and mounting the substrate on the substrate table by a substrate transport mechanism which is provided in the unit or receiving the substrate mounted on the substrate table and transporting the substrate into the unit by the transport mechanism.

13. The substrate processing apparatus according to claim 11 or 12, wherein

the substrate table is installed for the substrate transfer test at a location where a substrate transfer section of another unit which is used at a time of transfer of the substrate between the unit and another unit is located when the unit and another unit are assembled together.

14. The substrate processing apparatus according to any one of claims 11 to 13,
wherein

the substrate processing apparatus comprises a polishing unit configured to
polish the substrate and mount the polished substrate on a temporary table, and a
5 cleaning unit configured to clean and dry the substrate mounted on the temporary table,
and the unit control panel is provided in the cleaning unit,

the substrate table is installed for the substrate transfer test instead of the
temporary table at a location where the temporary table is located when the polishing
unit and the cleaning unit are assembled together, and

10 the test control section of the unit control panel provided in the cleaning unit
performs the substrate transfer test by receiving the substrate mounted on the substrate
table and transporting the substrate into the cleaning unit by a substrate transport
mechanism which is provided in the cleaning unit.

15. The substrate processing apparatus according to any one of claims 11 to 13,
15 wherein

the substrate processing apparatus comprises a polishing unit configured to
polish the substrate, a cleaning unit configured to clean and dry the substrate polished
by the polishing unit, and a loading/unloading unit configured to load the substrate onto
a lifter in the polishing unit and unload the substrate mounted on a substrate drying
20 module in the cleaning unit, and the unit control panel is provided in the
loading/unloading unit,

the substrate table is installed for the substrate transfer test instead of the lifter at a location where the lifter is located when the polishing unit and the loading/unloading unit are assembled together and is installed for the substrate transfer test instead of the drying module at a location where the drying module is located when the cleaning unit and the loading/unloading unit are assembled together, and

the test control section of the unit control panel provided in the loading/unloading unit performs the substrate transfer test by transporting the substrate placed in the loading/unloading unit to the substrate table and mounting the substrate on the substrate table by a substrate transport mechanism which is provided in the loading/unloading unit and receiving the substrate mounted on the substrate table and transporting the substrate into the loading/unloading unit by the transport mechanism.

16. The unit control panel according to claim 1, wherein

the substrate transfer test is performed by selecting a scenario for which a transport route for the substrate is presented as a plurality of blocks, selecting a scenario start position from which transport of the substrate is to be started by selecting any one of the blocks, transfer of the substrate based on the transport route and entering the number of repetitions of the scenario.

17. The unit control panel according to claim 16, wherein

the test control section determines whether a current block is the last block, and if the test control unit determines the current block is not the last block, the flow returns to the start of the block process to repeat processing.

18. The unit control panel according to claim 17, wherein

if the test control section determines that the current block is the last block of the scenario, the test control section determines whether the number of executions of the

scenario is not less than a set number.

19. The unit control panel according to claim 18, wherein

if the test control section determines that the number of executions of the scenario is less than the set number, the flow returns to the start of the block process to repeat processing from a first block.

20. The unit control panel according to claim 18, wherein

if the test control section determines that the number of executions of the scenario is not less than the set number, the test control section ends the process.

21. The unit control panel according to claim 1, wherein

the test control section determines whether a major failure has occurred in a unit executing the substrate transfer test,

if the test control section determines that a major failure has occurred in the unit executing the substrate transfer test, transport of the substrate is stopped, and

if the test control section determines that no major failure has occurred in the unit executing the substrate transfer test, transport of the substrate is performed as normal, and the process ends.